

Part Number: **BZX84CxxW-p-F (Date Code 0740+)**  
Weight (mg): 6

p = package designator  
See Data Sheet

XX= 10, 11, 12, 13, 15, 16, 18, 20, 22, 24, 27, 2V4,  
2V7, 30, 33, 36, 39, 3V0, 3V3, 3V6, 3V9, 4V3,  
4V7, 5V1, 5V6, 6V2, 6V8, 7V5, 8V2, 9V1

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Material(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.94%	0.0571	1000000	9352
Leadframe	Alloy 42	Fe	7439-89-6	57.65%	27.29%	1.666	576500	157299
		Ni	7440-02-0	41.00%			410000	111869
		Mn	7439-96-5	0.60%			6000	1637
		Cr(not Cr 6+)	7440-47-3	0.10%			1000	273
		Co	7440-48-4	0.50%			5000	1364
		Si	7440-21-3	0.15%			1500	409
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.03%	0.063	1000000	10318
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.15%	0.0089	1000000	1458
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	69.69%	4.2552	690000	480861
		Epoxy Resin	29690-82-2	14.00%			140000	97566
		Phenol Resin	9003-35-4	7.00%			70000	48783
		Mg(OH)2	1309-42-8	8.00%			80000	55752
		C	1333-86-4	0.20%			2000	1394
		others	----	1.80%			18000	12544
		Tin	7440-31-5	100.00%			0.91%	0.0557
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.91%	0.0557	1000000	9122
				<b>Total</b>	<b>100.00</b>	<b>6.1059</b>		<b>1000000</b>

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

\* The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold. These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, [Material Composition Declaration for Electronic Products](#).

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos	Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Azo compounds	Ozone Depleting Substances - Class II (HCFCs)
Cadmium and cadmium compounds	Perfluorooctane Sulphonate (PFOS) or related compounds
Certain Shortchain Chlorinated Paraffins	Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including <b>DecaBDE</b>
Chlorinated organic compounds	Polychlorinated Biphenyls (PCBs)
Hexavalent chromium compounds	Polychlorinated Naphthalenes (> 3 chlorine atoms)
Lead and lead compounds	Radioactive Substances
Mercury and mercury compounds	Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Organic tin compounds	Tributyl Tin Oxide (TBTO)